



10/762013

US Department of Commerce Patent and Trademark Office Form PTO-1449 (Modified)			Atty. Docket No.: 42390P9978C		Application No.: Not Yet Assigned	
			Applicant: Maeda et al.			
			Filing Date: Concurrently Herewith			
US Patent Documents						
Examiner's Initials	Date	Document Number	Name	Class	Sub- Class	Filing Date
CX	05/28/91	5,019,673	Juskey et al.			08/22/90
CX	05/05/92	5,111,279	Pasch et al.			08/30/90
CX	09/22/92	5,150,274	Okada et al.			07/09/91
CX	04/05/94	5,299,730	Pasch et al.			11/24/92
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CX	12/19/00	6,163,463	Marrs			05/13/98
Foreign Patent Documents						
Examiner's Initials	Date	Document Number	Country	Class	Sub- Class	Translation
CX	06/23/88	JP63151033	Japan			
Other Documents (Including Author, Title, Date, Pertinent Pages, etc.)						
Examiner 			Date Considered 11/9/05			

Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw a line through the citation if not in conformance and not considered. Include a copy of this form with the next communication to the applicant

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Examiner's Initials	Date	Document Number	Name	Class	Sub- Class	Filing Date
OX	01/06/98	5,704,116	Gamota et al.			
OX	04/17/01	6,217,671	Henderson et al.			
OX	05/02/00	6,057,168	Seyama et al.			
OX	01/11/00	6,013,572	Hur et al.			
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OX		Pooya Tadayon, Sort Test Technology Development, Intel Corporation. "Thermal Challenges Diring Microprocessor Testing". Intel Technology Journal Q3, 2000. Pgs. 1-8.				
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Examiner 			Date Considered 11/9/05			

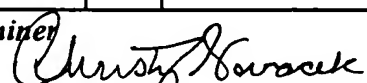
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OK	07/28/98	5,785,234	Weiss et al.				
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Examiner <i>Christy Horvack</i>				Date Considered 11/9/05			

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OK		12/24/91	5,074,920	Gonsiorawski et al.			
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Examiner's Initials		Date	Document Number	Country	Class	Sub-Class	Translation
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Examiner Christy Horacek				Date Considered 11/9/05			

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CK		05/09/00	6,059,894	Pendse			
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Based on PTO/SE/088 (08-03) as modified by Blakely, Solokoff, Taylor & Zafman (wtr) 08/11/2003.
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